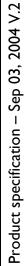


# **DATA SHEET**

**GENERAL PURPOSE CHIP RESISTORS** 

RC0805 (Pb Free) 5%; 1%







**YAGEO** 



### **Chip Resistor Surface Mount**

: |

SERIES

0805 (Pb Free)

#### SCOPE

This specification describes RC0805 series chip resistors with lead-free terminations made by thick film process.

#### ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

#### **YAGEO ORDERING CODE**

#### CTC CODE

RC0805  $\underline{X} \underline{X} \underline{X} \underline{X} \underline{XX} \underline{XXXX} \underline{L}$ 

(1) (2) (3) (4) (5)

(I) TOLERANCE

 $F = \pm 1\%$  $J = \pm 5\%$ 

(2) PACKAGING TYPE

R = Paper/PE taping reel

(3) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(4) TAPING REEL

07 = 7 inch dia. Reel

10 = 10 inch dia. Reel (not preferred)

13 = 13 inch dia, Reel

(5) RESISTANCE VALUE

5R6, 56R, 560R, 5K6, 56K, 22M.

(6) RESISTOR TERMINATIONS

L = Lead free terminations (pure Tin)

#### **ORDERING EXAMPLE**

The ordering code of a RC0805 chip resistor, value 56  $\Omega$  with ±1% tolerance, supplied in 7-inch tape reel is: RC0805FR-0756RL.

#### NOTE

- The "L" at the end of the code is only for ordering. On the reel label, the standard CTC will be mentioned an additional stamp "LFP"= lead free production.
- Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)





# **Chip Resistor Surface Mount**

SERIES

0805 (Pb Free)

#### MARKING

#### RC0805



E-24 series: 3 digits

First two digits for significant figure and 3rd digit for number of zeros



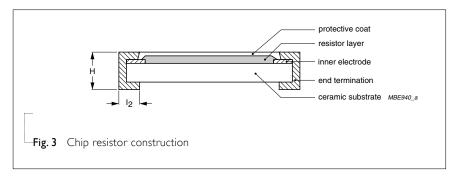
Both E-24 and E-96 series: 4 digits

First three digits for significant figure and 4th digit for number of zeros

For marking codes, please see EIA-marking code rules in data sheet "Chip resistors instruction".

#### **CONSTRUCTION**

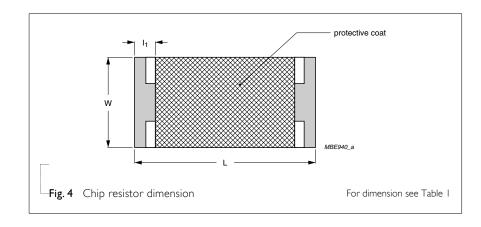
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the



resistance value. Finally, the two external terminations (pure Tin) are added. See fig. 3.

#### **DIMENSIONS**

RC0805
2.00 ±0.10
1.25 ±0.10
0.50 ±0.10
0.35 ±0.20
0.35 ±0.20





# Chip Resistor Surface Mount RC SERIES 0805 (Pb Free)

#### **ELECTRICAL CHARACTERISTICS**

Table 2

CHARACTERISTICS	F	RC0805 1/8 W
Operating Temperature Range	-55	°C to +155 °C
Maximum Working Voltage		150 V
Maximum Overload Voltage		300 V
Dielectric Withstanding Voltage		300 V
	5% (E24)	I $\Omega$ to 22 M $\Omega$
Resistance Range	1% (E96)	I $\Omega$ to I0 M $\Omega$
	Zero Ohm Ju	ımper < 0.05 Ω
Temperature Coefficient	$10 \Omega < R \le 10 M\Omega$	±100 ppm/°C
Temperature Coemcient	$R \le 10 \Omega$ ; $R > 10 M\Omega$	±200 ppm/°C
Jumper Criteria	Rated Current	2.0 A
Jumper Criteria	Maximum Current	5.0 A

# <u>FOOTPRINT AND SOLDERING</u> <u>PROFILES</u>

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

#### **ENVIRONMENTAL DATA**

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data".

#### PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL
RC0805	Paper / PE Taping Reel (R)	7" (178 mm)	5,000 units
		10" (254 mm) / not preferred	10,000 units
		13" (330 mm)	20,000 units

#### NOTE

1. For Paper/PE tape and reel specification/dimensions, please see the special data sheet "Packing" document.

#### **FUNCTIONAL DESCRIPTION**

#### **POWER RATING**

RC0805 rated power at 70°C is 1/8 W

#### **RATED VOLTAGE**

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

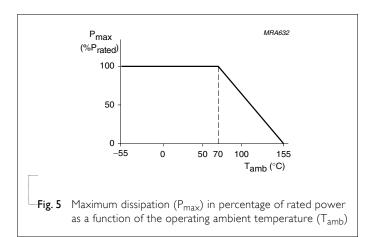
$$V=\sqrt{(P \times R)}$$

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value  $(\Omega)$ 



#### **PULSE LOADING CAPABILITIES**

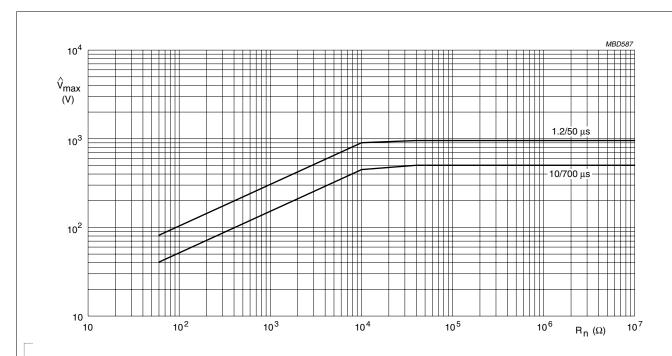


Fig. 6 Maximum permissible peak pulse voltage without failing to open circuit' in accordance with DIN IEC 60040 (CO) 533 for type: RC0805

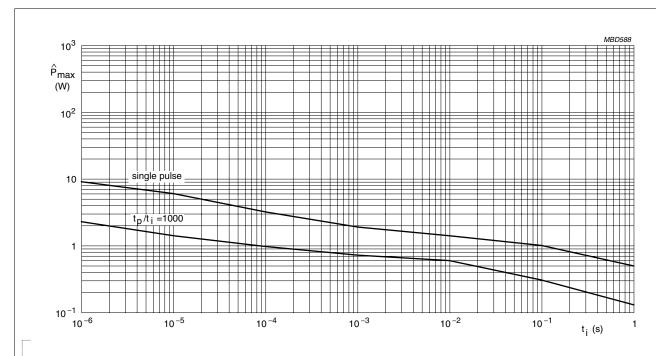


Fig. 7 Pulse on a regular basis for type: RC0805; maximum permissible peak pulse power as a function of pulse duration for single pulse and repetitive pulse tp/ti = 1000

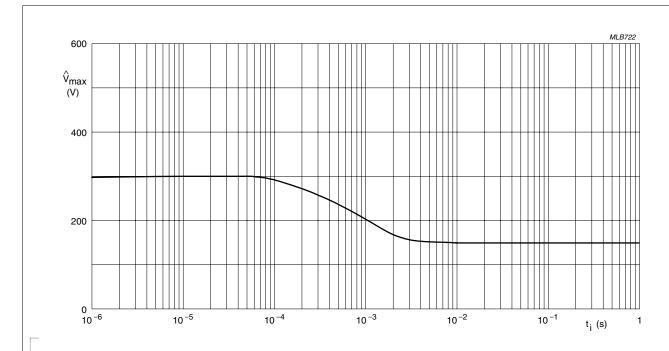


Fig. 8 Pulse on a regular basis for type: RC0805; maximum permissible peak pulse voltage as a function of pulse duration



### TESTS AND REQUIREMENTS

**Table 4** Test condition, procedure and requirements

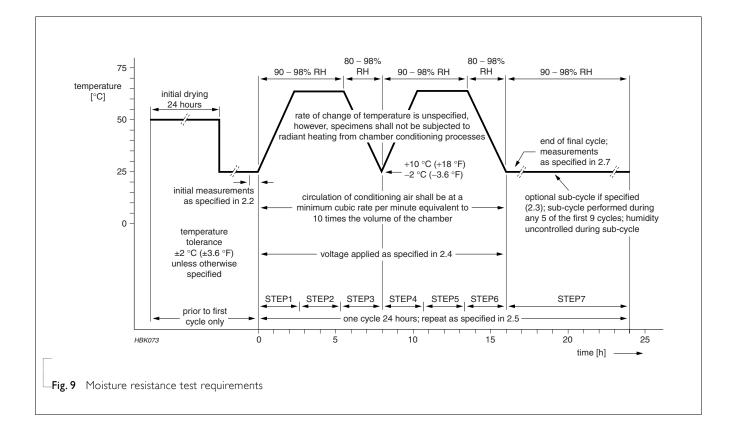
TEST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Temperature Coefficient of	MIL-STD-202F-method 304;	At +25/-55 °C and +25/+125 °C	Refer to table 3	
Resistance	JIS C 3202 1.0			
(T.C.R.)		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$		
		Where $t_1$ =+25 °C or specified room temperature		
		$t_2$ =–55 °C or +125 °C test temperature		
		$R_1$ =resistance at reference temperature in ohms		
		R <sub>2</sub> =resistance at test temperature in ohms		
Thermal Shock	MIL-STD-202F-method 107G;	At -65 (+0/-10) °C for 2 minutes and at +155	$\pm (0.5\% \pm 0.05~\Omega)$ for 1% tol.	
	IEC 60115-1 4.19	(+10/-0) °C for 2 minutes; 25 cycles	$\pm (1.0\% {+} 0.05~\Omega)$ for 5% tol.	
Low	MIL-R-55342D-Para 4.7.4	At -65 (+0/-5) °C for I hour, RCWV applied	$\pm (0.5\% \pm 0.05~\Omega)$ for 1% tol .	
Temperature		for 45 (+5/–0) minutes	$\pm (1.0\% + 0.05~\Omega)$ for 5% tol.	
Operation			No visible damage	
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room	$\pm$ (1.0%+0.05 $\Omega$ ) for 1% tol.	
Overload	IEC 60115-1 4.13	temperature	$\pm (2.0\% + 0.05~\Omega)$ for 5% tol.	
			No visible damage	
Insulation	MIL-STD-202F-method 302;	RCOV for I minute	≥10 GΩ	
Resistance IEC 60115-1 4.6.1.1 Type		Type RC0805		
		Voltage (DC) 300 V		
Dielectric	MIL-STD-202F-method 301;	Maximun voltage (V <sub>rms</sub> ) applied for 1 minute	No breakdown or flashover	
Withstand Voltage	IEC 60115-1 4.6.1.1	Type RC0805		
		Voltage (AC) 300 V <sub>rms</sub>		
Resistance to Soldering	MIL-STD-202F-method 210C;	Unmounted chips; 260 ±5 °C for 10 ±1 seconds	$\pm (0.5\% + 0.05 \ \Omega)$ for 1% tol.	
Soldering Heat	_	IEC 60115-1 4.18	Seconds	$\pm (1.0\% + 0.05 \ \Omega)$ for 5% tol. No visible damage
Life	MIL-STD-202F-method 108A;	At 70±2 °C for 1,000 hours; RCWV applied for	$\pm$ (1%+0.05 $\Omega$ ) for 1% tol.	
	IEC 60115-1 4.25.1	1.5 hours on and 0.5 hour off	$\pm (3\% + 0.05 \ \Omega)$ for 5% tol.	



# Chip Resistor Surface Mount RC SERIES 0805 (Pb Free)

ST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% cove	ered)
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds	No visible damage	
Bending Strength	JIS ⊂ 5202.6.14;	Resistors mounted on a 90 mm glass epoxy	$\pm$ (1.0%+0.05 $\Omega$ ) for 1% tol.	
	IEC 60115-1 4.15	resin PCB (FR4)	$\pm (1.0\% + 0.05 \ \Omega)$ for 5%	á tol.
		Bending: 5 mm	No visible damage	
Resistance to Solvent	MIL-STD-202F-method 215;	Isopropylalcohol (C <sub>3</sub> H <sub>7</sub> OH) or dichloromethane	No smeared	
	IEC 60115-1 4.29	(CH <sub>2</sub> Cl <sub>2</sub> ) followed by brushing		
Noise	JIS C 5202 5.9;	Maximum voltage (V <sub>ms</sub> ) applied.	Resistors range	Value
	IEC 60115-1 4.12		R < 100 Ω	10 dB
			$100 \Omega \le R < 1 K\Omega$	20 dB
			$1 \text{ K}\Omega \leq R < 10 \text{ K}\Omega$	30 dB
			10 KΩ ≤ R < 100 KΩ	40 dB
			$100 \text{ K}\Omega \leq R < 1 \text{ M}\Omega$	46 dB
			$1 \text{ M}\Omega \leq R \leq 22 \text{ M}\Omega$	48 dB
Humidity	JIS C 5202 7.5;	1,000 hours; 40±2 °C; 93(+2/–3)% RH	+(0.5%+0.05. <b>Q</b> ) for 1%	( +al
Humidity (steady state)	JIS C 5202 7.5; IEC 60115-8 4.24.8	I,000 hours; 40±2 °C; 93(+2/–3)% RH RCWV applied for I.5 hours on and 0.5 hour off	$\pm$ (0.5%+0.05 $\Omega$ ) for 1% $\pm$ (2.0%+0.05 $\Omega$ ) for 5%	
•	•	, ,	,	
(steady state)	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off	$\pm (2.0\% + 0.05 \ \Omega)$ for 5%	
(steady state)  Leaching  Intermittent	IEC 60115-8 4.24.8 EIA/IS 4.13B;	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at $260\pm5$ °C Dipping time: $30\pm1$ seconds	$\pm (2.0\% + 0.05 \ \Omega)$ for 5%	ś tol.
(steady state)  Leaching	IEC 60115-8 4.24.8  EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at $260\pm5$ °C Dipping time: $30\pm1$ seconds	$\pm (2.0\% + 0.05 \ \Omega)$ for 5% No visible damage	ś tol.
(steady state)  Leaching  Intermittent	IEC 60115-8 4.24.8  EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at $260\pm5$ °C Dipping time: $30\pm1$ seconds  At room temperature; $2.5 \times$ RCWV applied for 1 second on and 25 seconds off; total 10,000	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1%	ś tol.
Leaching  Intermittent Overload  Resistance to Vibration  Moisture	IEC 60115-8 4.24.8  EIA/IS 4.13B; IEC 60115-8 4.18  JIS C 5202 5.8	RCWV applied for 1.5 hours on and 0.5 hour off  Solder bath at 260±5 °C  Dipping time: 30±1 seconds  At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1%	6 tol. 6 tol. 6 tol.
Leaching  Intermittent Overload  Resistance to Vibration	IEC 60115-8 4.24.8  EIA/IS 4.13B; IEC 60115-8 4.18  JIS C 5202 5.8  On request	RCWV applied for 1.5 hours on and 0.5 hour off  Solder bath at 260±5 °C  Dipping time: 30±1 seconds  At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles  On request	$\pm (2.0\% + 0.05~\Omega)$ for $5\%$ No visible damage $\pm (1.0\% + 0.05~\Omega)$ for $1\%$ $\pm (2.0\% + 0.05~\Omega)$ for $5\%$	6 tol. 6 tol. 6 tol.

0805 (Pb Free)







# Chip Resistor Surface Mount RC SERIES 0805 (Pb Free)

# REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	Sep 03, 2004	-	- Test method and procedure updated
			- PE tape added (paper tape will be replaced by PE tape)